

DOCKET NO. 01-C-084 (STMI01-01084)
Customer No. 30425

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Harry Michael Siegel, et al.
Serial No. : 10/066,245
Filed : January 31, 2002
For : METHOD FOR USING A PRE-FORMED FILM IN A TRANSFER
MOLDING PROCESS FOR AN INTEGRATED CIRCUIT (AS
AMENDED)
Group No. : 1791
Examiner : Edmund H. Lee
Confirmation No. : 2782

MAIL STOP ISSUE FEE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT UNDER 37 C.F.R. § 1.312

Pursuant to 37 C.F.R. § 1.312, Applicant respectfully requests amendment the above-identified application as follows: